









PRODUCT DATASHEET



- ► PLCC6 SMD
- ➤ 3433 1.92t Series
- ► Gold White (PC Amber) 1900K

NOW40S15ZPC





3433 1.92t Series





AEC-Q102

FEATURES:

Package: PLCC6 Top View White SMT Package

Forward Current: 140mA Forward Voltage (typ.): 3.1V

Luminous Intensity (typ.): 12840mcd@140mA

Colour: Cool White

Colour Temperature (CCT): 1700~2700K

Viewing angle: 120°

Materials:

Resin: Silicon (Yellow Diffused)

L/T Finish: Ag plated

Operating Temperature: -40~+105°C

Storage Temperature: -40~+105°C

ESD (HBM): 6kV

Grouping parameters:

Forward voltage

Luminous intensity

CIE Chromaticity

Soldering methods: IR Reflow

MSL: acc. to JEDEC Level 2a (J-STD20D)

Packing: 12mm tape with max.1000/reel, ø180mm (7")

APPLICATIONS:

- Automotive
- **Decorative Lighting**
- Backlighting
- Indicator
- Dashboard
- Display



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	l _F	240	mA
Pulse Forward Current Duty 1/10, width 0.1ms	IPF	700	mA
Reverse Voltage	V _R	5	V
Reverse Current @10V	I _R	10	μΑ
Junction Temperature	Tj	125	°C
Electrostatics Discharge (HBM)	ESD	6000	V
Operating Temperature	T _{OPR}	-40~+105	°C
Storage Temperature	Тѕтс	-40~+105	°C
Soldering Temperature	T _{SD}	260	°C
Colour Rendering Index	CRI	70	

Electrical & Optical Characteristics (Ta=25°C)

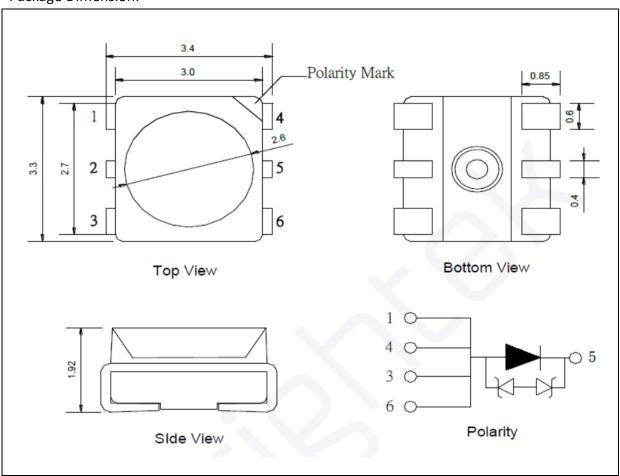
Darameter		Values	Unit	Test			
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition	
Forward Voltage	V _F	2.7	3.1	3.6	V	I _F =140mA	
Luminous Intensity	lv	6000	12840		mcd	I _F =140mA	
Luminous Flux	Ф۷		40		lm	I _F =140mA	
Chromaticity	Х		0.5751			1 140 1	
Coordinates	Υ		0.4150			I _F =140mA	
Colour Temperature	ССТ		1900		К	I _F =140mA	
Viewing Angle	2θ _{1/2}		120		deg	I _F =140mA	

^{1.} Luminous intensity (I_V) $\pm 10\%$, Forward Voltage (V_F) $\pm 0.1V$, Viewing angle($2\theta_{1/2}$) $\pm 5\%$, Wavelength ± 1 nm



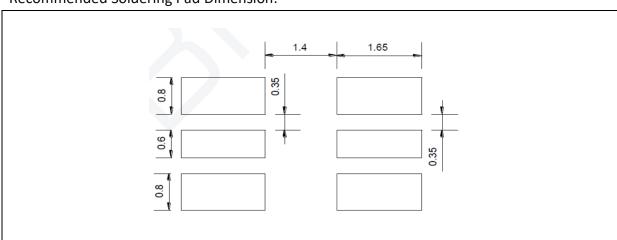
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 140mA):

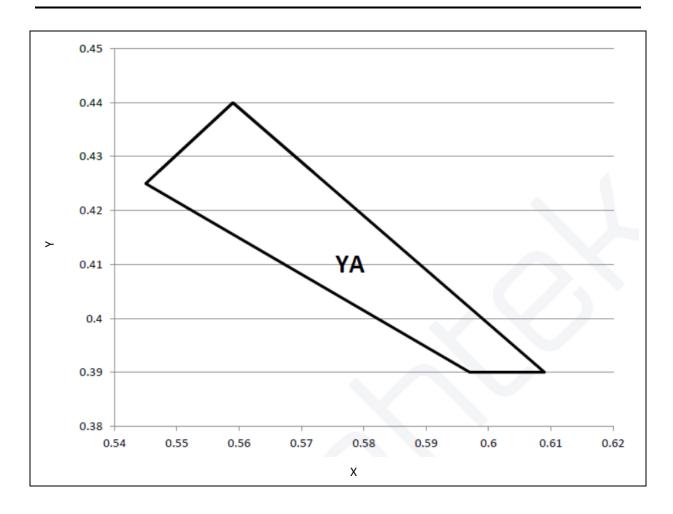
Code	Min.	Max.	Unit
Н	2.7	3.0	
I	3.0	3.3	V
J	3.3	3.6	

Luminous Intensity Classifications (I_F = 140mA):

Code	Min.	Max.	Unit
22	6000	7800	
23	7800	10100	
24	10100	13130	mcd
25	13130	17000	
26	17000	22110	



CIE CHROMATICITY DIAGRAM:

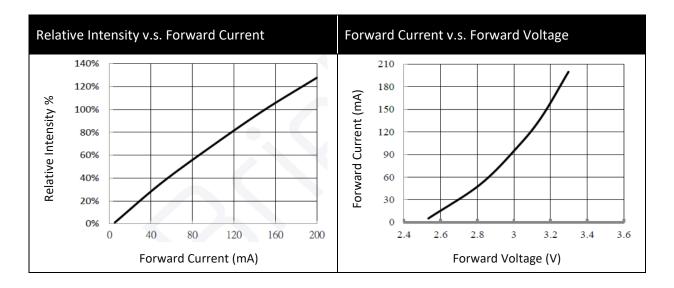


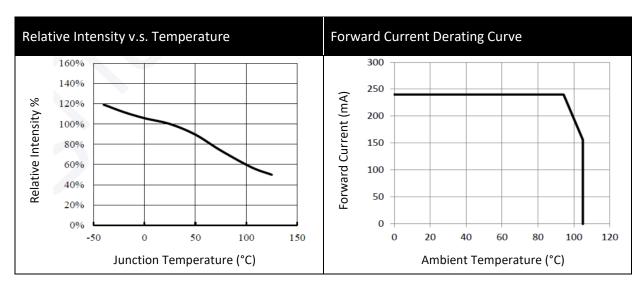
Chromaticity Coordinates Classifications (IF = 140mA):

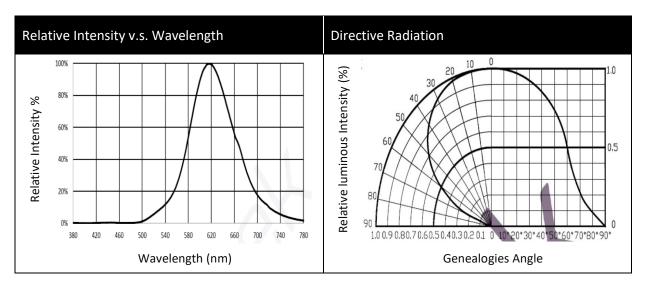
	-	l	2	2	3	3	4	1
	Х	Υ	Х	Υ	Х	Υ	Х	Υ
YA	0.6090	0.3900	0.5970	0.3900	0.5450	0.4250	0.5590	0.4400



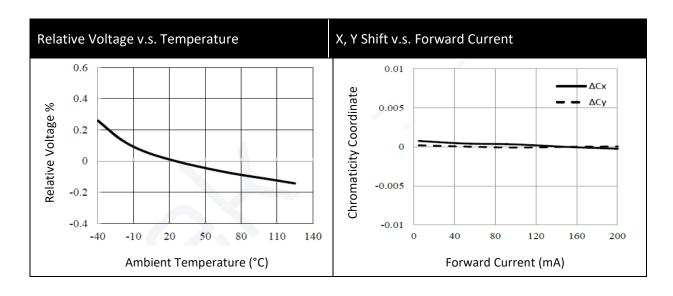
ELECTRO-OPTICAL CHARACTERISTICS:

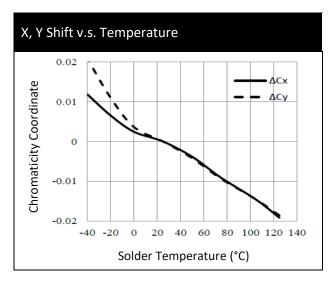








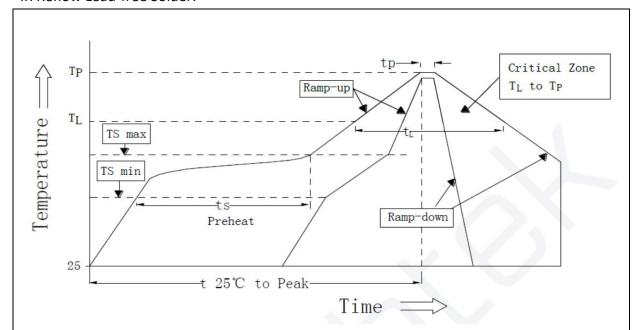






RECOMMENDED SOLDERING PROFILE:

IR Reflow Lead-free Solder:



Description of the second	Symbol	Pb-	**		
Profile Feature		Min.	Recommendation	Max.	Unit
Ramp-up rate to preheat (25°C to 150°C)	1-1		2	3	K/s
Time t _S (T _{S min} to T _{S max})	ts	60	100	120	S
Ramp-up rate to peak (T _{S max} to T _P)	-	-	2	3	K/s
Liquidus temperature	T_{L}	-	217	-	°C
Time above liquidus temperature	t _L	=	80	100	S
Peak temperature	T _P	-	245	260	°C
Time within 5 °C of the specified peak temperature T _P - 5 K	t _P	-	-	10	S
Ramp-down Rate (T _P to 100 °C)	-	-	3	4	K/s
Time 25 °C to T _P	-	-	-	480	S

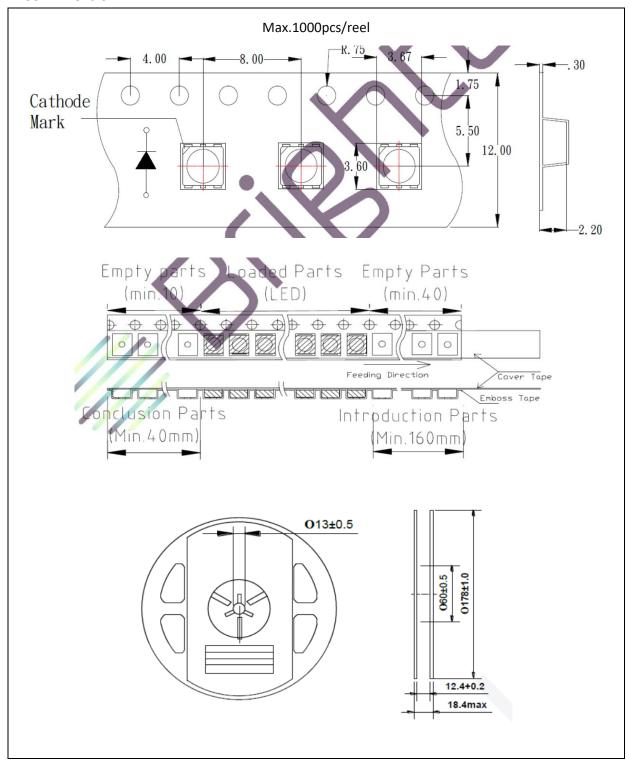
Note:

- 1. Maximum reflow soldering: 3 times.
- 2. Recommended reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

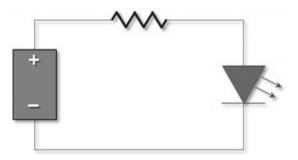
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 6hrs and <5%RH, for reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	03/11/2020	Datasheet set-up.
A1.1	04/06/2022	New datasheet format.